1-Bit 20 Mb/s Dual-Supply Level Translator

The NLSX4401DFT2G is a 1-bit configurable dual-supply bidirectional auto sensing translator that does not require a directional control pin. The I/O V_{CC} and I/O V_{L} ports are designed to track two different power supply rails, V_{CC} and V_{L} respectively. Both the V_{CC} and V_{L} supply rails are configurable from 1.65 V to 5.5 V. This allows voltage logic signals on the V_{L} side to be translated into lower, higher or equal value voltage logic signals on the V_{CC} side, and vice-versa.

The NLSX4401DFT2G translator has integrated 10 k Ω pull-up resistors on the I/O lines. The integrated pull-up resistors are used to pull up the I/O lines to either V_L or V_{CC} . The NLSX4401 is an excellent match for open-drain applications such as the I²C communication bus.

Features

- ullet V_L can be Less than, Greater than or Equal to V_{CC}
- Wide V_{CC} Operating Range: 1.65 V to 5.5 V
 Wide V_L Operating Range: 1.65 V to 5.5 V
- High Speed with 24 Mb/s Guaranteed Date Rate
- Low Bit-to-Bit Skew
- Enable Input and I/O Pins are Overvoltage Tolerant (OVT) to 5.5 V
- Non-preferential Powerup Sequencing
- Partial Power-Off Protection I/Os at High Impedance with Either Supply at 0 V
- Integrated 10 kΩ Pull–up Resistors
- Small Space Saving Packages:

SC-88/SC70-6/SOT-363 Package

• These Devices are Pb-Free and are RoHS Compliant

Typical Applications

- I²C, SMBus, PMBus
- Low Voltage ASIC Level Translation
- Mobile Phones, PDAs, Cameras

Important Information

- ESD Protection for All Pins
 - Human Body Model (HBM) > 5000 V



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SC-88 2.10 x 2.0 CASE 419B



XXX = Specific Device Code

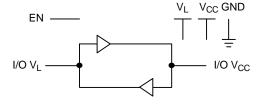
M = Date Code*

= Pb-Free Package

(Note: Microdot may be in either location)

*Date Code orientation and/or position may vary depending upon manufacturing location.

LOGIC DIAGRAM



ORDERING INFORMATION

Device	Package	Shipping [†]
NLSX4401DFT2G	SC-88 (Pb-Free)	3000 / Tape & Reel

†For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specification Brochure, BRD8011/D.

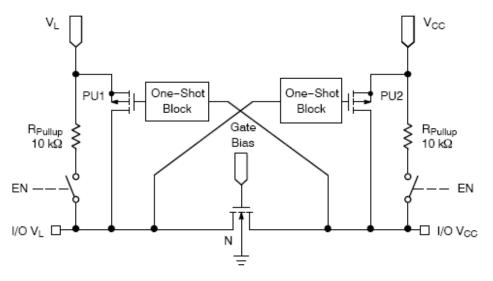
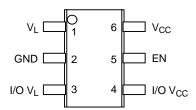


Figure 1. Block Diagram (1 I/O Line)



SC-88 / SC70-6 / SOT-363 (Top Through View)

Figure 2. Pinout Diagram

PIN ASSIGNMENT

Pins	Description
V _{CC}	V _{CC} Supply Voltage
VL	V _L Supply Voltage
GND	Ground
EN	Output Enable, Referenced to V _L
I/O V _{CC}	I/O Port, Referenced to V _{CC}
I/O V _L	I/O Port, Referenced to V _L

FUNCTION TABLE

EN	Operating Mode
٦	Hi–Z
Н	I/O Buses Connected

MAXIMUM RATINGS

Symbol	Parameter	Value	Condition	Unit
V _{CC}	DC Supply Voltage	-0.5 to +7.0		V
V _L	DC Supply Voltage	-0.5 to +7.0		V
I/O V _{CC}	V _{CC} -Referenced DC Input/Output Voltage	-0.5 to +7.0		V
I/O V _L	V _L -Referenced DC Input/Output Voltage	-0.5 to +7.0		V
V _{EN}	Enable Control Pin DC Input Voltage	-0.5 to +7.0		V
I _{I/O_SC}	Short-Circuit Duration (I/O V _L and I/O V _{CC} to GND)	±50	Continuous	mA
I _{I/OK}	Input/Output Clamping Current (I/O V _L and I/O V _{CC})	-50	V _{I/O} < 0	mA
T _{STG}	Storage Temperature	-65 to +150		°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

RECOMMENDED OPERATING CONDITIONS

Symbol	Parameter	Min	Max	Unit
V _{CC}	Positive DC Supply Voltage	1.5	5.5	V
V _L	Positive DC Supply Voltage	1.5	5.5	V
V _{EN}	Enable Control Pin Voltage	GND	5.5	V
V _{IO_VCC}	I/O Pin Voltage (Side referred to V _{CC})	GND	5.5	V
V _{IO_VL}	I/O Pin Voltage (Side referred to V _L)	GND	5.5	V
Δt/ΔV	Input Transition Rise and Fall Rate A- or B-Ports, Push-Ports, Pus	ull Driving ntrol Input	10 10	ns/V
T _A	Operating Temperature Range	-55	+125	°C

Functional operation above the stresses listed in the Recommended Operating Ranges is not implied. Extended exposure to stresses beyond the Recommended Operating Ranges limits may affect device reliability.

DC ELECTRICAL CHARACTERISTICS ($V_L = 1.65 \text{ V}$ to 5.5 V and $V_{CC} = 1.65 \text{ V}$ to 5.5 V, unless otherwise specified) (Note 1)

			-55°C to +125°C			
Symbol	Parameter	Test Conditions (Note 2)	Min	Тур	Max	Unit
V _{IHC}	I/O V _{CC} Input HIGH Voltage		V _{CC} - 0.4	-	_	V
V _{ILC}	I/O V _{CC} Input LOW Voltage		-	-	0.15	V
V _{IHL}	I/O VL Input HIGH Voltage		V _L - 0.4	-	-	V
V _{ILL}	I/O VL Input LOW Voltage		-	-	0.15	V
V _{IH}	Control Pin Input HIGH Voltage		0.65 * V _L	-	_	V
V _{IL}	Control Pin Input LOW Voltage	V _L = 1.65 V to 1.95 V V _L = 2.3 V to 5.5 V	_ _	_ _	0.25 * V _L 0.35 * V _L	V
V _{OHC}	I/O Vcc Output HIGH Voltage	I/O V _{CC} source current = 20 μA	2/3 * V _{CC}	-	_	V
V _{OLC}	I/O Vcc Output LOW Voltage	I/O V _{CC} sink current = 1 mA	-	1	0.4	V
V _{OHL}	I/O V∟Output HIGH Voltage	I/O V _L source current = 20 μA	2/3 * V _L	-	-	V
V _{OLL}	I/O V _∟ Output LOW Voltage	I/O V _L sink current = 1 mA	-	-	0.4	V
I _{QVCC}	V _{CC} Supply Current	I/O V_{CC} and I/O V_L unconnected, V_{EN} = V_L V_L = 5.5 V, V_{CC} = 0 V V_L = 0 V, V_{CC} = 5.5 V	- - -	0.5 - -	3.0 -1.0 1.0	μΑ
I _{QVL}	V _⊥ Supply Current	I/O V _{CC} and I/O V _L unconnected, V _{EN} = V _L $ \begin{array}{c} V_L = 5.5 \text{ V, V}_{CC} = 0 \text{ V} \\ V_L = 0 \text{ V, V}_{CC} = 5.5 \text{ V} \end{array} $	- - -	0.3 - -	3.0 1.0 –1.0	μΑ
I _{TS-VCC}	V _{CC} Tristate Output Mode	I/O V_{CC} and I/O V_L unconnected, $V_{EN} = GND$	-	0.1	1.5	μΑ
I _{TS-VL}	V _L Tristate Output Mode Supply Current	I/O V_{CC} and I/O V_{L} unconnected, $V_{EN} = GND$	-	0.1	1.5	μΑ
I _I	Enable Pin Input Leakage Current		-	-	1.0	μΑ
I _{OFF}	I/O Power-Off Leakage Current	I/O V_{CC} Port, $V_{CC} = 0$ V, $V_{L} = 0$ to 5.5 V	-	-	1.0	μΑ
		I/O VL Port, VCC = 0 to 5.5 V, $V_L = 0 \text{ V}$	-	-	1.0	
I _{OZ}	I/O Tristate Output Mode Leakage Current		-	0.1	1.0	μΑ
R _{PU}	Pull–Up Resistors I/O V _L and V _C		-	10	_	kΩ

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Typical values are for V_L = +1.8 V, V_{CC} = +3.3 V and T_A = +25°C.

2. All units are production tested at T_A = +25°C. Limits over the operating temperature range are guaranteed by design.

TIMING CHARACTERISTICS - RAIL-TO-RAIL DRIVING CONFIGURATIONS

(I/O test circuit of Figures 3 and 4, C_{LOAD} = 15 pF, driver output impedance \leq 50 Ω , R_{LOAD} = 1 M Ω)

				-40°C to +85 ° (Notes 3 & 4		
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _L = 1.65 V,	V _{CC} = 1.65 V	•			•	
t _{RVCC}	I/O V _{CC} Rise Time			9	32	ns
t _{FVCC}	I/O V _{CC} Fall Time			11	20	ns
t _{RVL}	I/O V _L Rise Time			20	30	ns
t_{FVL}	I/O V _L Fall Time			10	13	ns
t _{PDVL} VCC	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			7	16	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			12	15	ns
t _{PZL} , t _{PZH}	Enable Time				269	ns
t _{PLZ} , t _{PHZ}	Disable Time				300	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		15			Mbps
V _L = 1.65 V,	V _{CC} = 5.5 V	-	•	1		
t _{RVCC}	I/O V _{CC} Rise Time			9	12	ns
t _{FVCC}	I/O V _{CC} Fall Time			17	30	ns
t _{RVL}	I/O V _L Rise Time			8	10	ns
t _{FVL}	I/O V _L Fall Time			5	9	ns
t _{PDVL-VCC}	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			14	24	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			4	6	ns
t _{PZL} , t _{PZH}	Enable Time				66	ns
t _{PLZ} , t _{PHZ}	Disable Time				250	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		20			Mbps
V _L = 1.8 V, V	/ _{CC} = 2.8 V	·				•
t _{RVCC}	I/O V _{CC} Rise Time			11	18	ns
t _{FVCC}	I/O V _{CC} Fall Time			10	15	ns
t _{RVL}	I/O V _L Rise Time			12	15	ns
t_{FVL}	I/O V _L Fall Time			5	8	ns
t _{PDVL-VCC}	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			7	10	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			1	12	ns
t _{PZL} , t _{PZH}	Enable Time				100	ns
t _{PLZ} , t _{PHZ}	Disable Time				300	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		20			Mbps
V _L = 2.5 V, V	/ _{CC} = 3.6 V	·				
t _{RVCC}	I/O V _{CC} Rise Time			8	12	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 3. Typical values are for the specified V_L and V_{CC} at $T_A = +25^{\circ}C$. All units are production tested at $T_A = +25^{\circ}C$. 4. Limits over the operating temperature range are guaranteed by design.
- 5. Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (I/O_VLn or I/O_VCCn) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW). Skew is defined by applying a single input to the two input channels and measuring the difference in propagation delays between the output channels.

TIMING CHARACTERISTICS - RAIL-TO-RAIL DRIVING CONFIGURATIONS (continued)

(I/O test circuit of Figures 3 and 4, C_{LOAD} = 15 pF, driver output impedance \leq 50 Ω , R_{LOAD} = 1 M Ω)

				-40°C to +85 (Notes 3 & 4		
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _L = 2.5 V, V	/ _{CC} = 3.6 V	<u>.</u>				•
t _{FVCC}	I/O V _{CC} Fall Time			8	12	ns
t _{RVL}	I/O V _L Rise Time			7	10	ns
t _{FVL}	I/O V _L Fall Time			5	7	ns
t _{PDVL} -VCC	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			7	10	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			5	8	ns
t _{PZL} , t _{PZH}	Enable Time				74	ns
t _{PLZ} , t _{PHZ}	Disable Time				225	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		24			Mbps
V _L = 2.8 V, V	/ _{CC} = 1.8 V	-	1	1		<u></u>
t _{RVCC}	I/O V _{CC} Rise Time			13	20	ns
t _{FVCC}	I/O V _{CC} Fall Time			7	10	ns
t _{RVL}	I/O V _L Rise Time			8	13	ns
t _{FVL}	I/O V _L Fall Time			9	15	ns
t _{PDVL} -VCC	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			6	9	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			7	12	ns
t _{PZL} , t _{PZH}	Enable Time				103	ns
t _{PLZ} , t _{PHZ}	Disable Time				250	ns
tppskew	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		24			Mbps
V _L = 3.6 V, V	/ _{CC} = 2.5 V	-	1	1		<u></u>
t _{RVCC}	I/O V _{CC} Rise Time			9	12	ns
t _{FVCC}	I/O V _{CC} Fall Time			6	9	ns
t _{RVL}	I/O V _L Rise Time			6	12	ns
t _{FVL}	I/O V _L Fall Time			7	12	ns
t _{PDVL} -VCC	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			5	7	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			6	9	ns
t _{PZL} , t _{PZH}	Enable Time				77	ns
t _{PLZ} , t _{PHZ}	Disable Time				250	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		24			Mbps
V _L = 5.5 V, V	/ _{CC} = 1.65 V	·	•	•		
t _{RVCC}	I/O V _{CC} Rise Time			13	20	ns
t _{FVCC}	I/O V _{CC} Fall Time			6	9	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- Typical values are for the specified V_L and V_{CC} at T_A = +25°C. All units are production tested at T_A = +25°C.
 Limits over the operating temperature range are guaranteed by design.
- 5. Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (I/O_VLn or I/O_VCCn) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW). Skew is defined by applying a single input to the two input channels and measuring the difference in propagation delays between the output channels.

TIMING CHARACTERISTICS - RAIL-TO-RAIL DRIVING CONFIGURATIONS (continued)

(I/O test circuit of Figures 3 and 4, C_{LOAD} = 15 pF, driver output impedance \leq 50 Ω , R_{LOAD} = 1 M Ω)

Symbol			-40°C to +85°C (Notes 3 & 4)			
	Parameter	Test Conditions	Min	Тур	Max	Unit
V _L = 5.5 V, V	_{CC} = 1.65 V	<u>.</u>				
t _{RVL}	I/O V _L Rise Time			8	10	ns
t _{FVL}	I/O V _L Fall Time			22	37	ns
t _{PDVL-VCC}	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			9	13	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			13	25	ns
t _{PZL} , t _{PZH}	Enable Time					ns
t _{PLZ} , t _{PHZ}	Disable Time					ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		20			Mbps
V _L = 5.5 V, V	_{CC} = 5.5 V					
t _{RVCC}	I/O V _{CC} Rise Time			5	7	ns
t _{FVCC}	I/O V _{CC} Fall Time			6	8	ns
t _{RVL}	I/O V _L Rise Time			5	7	ns
t _{FVL}	I/O V _L Fall Time			5	8	ns
t _{PDVL-VCC}	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			4	6	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			4	6	ns
t _{PZL} , t _{PZH}	Enable Time				30	ns
t _{PLZ} , t _{PHZ}	Disable Time				225	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		24			Mbps

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 3. Typical values are for the specified V_1 and V_{CC} at $T_A = +25^{\circ}C$. All units are production tested at $T_A = +25^{\circ}C$.
- 4. Limits over the operating temperature range are guaranteed by design.
- 5. Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (I/O_VLn or I/O_VCCn) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW). Skew is defined by applying a single input to the two input channels and measuring the difference in propagation delays between the output channels.

TIMING CHARACTERISTICS - OPEN DRAIN DRIVING CONFIGURATIONS

(I/O test circuit of Figures 5 and 6, C_{LOAD} = 15 pF, driver output impedance \leq 50 Ω , R_{LOAD} = 1 M Ω)

				0°C to +85 Notes 6 & 7	_	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _L = 1.65 V,	V _{CC} = 1.65 V					
t _{RVCC}	I/O V _{CC} Rise Time			55	70	ns
t _{FVCC}	I/O V _{CC} Fall Time			7	14	ns
t _{RVL}	I/O V _L Rise Time			50	65	ns
t _{FVL}	I/O V _L Fall Time			7	12	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 6. Typical values are for the specified V_L and V_{CC} at $T_A = +25^{\circ}C$. All units are production tested at $T_A = +25^{\circ}C$.
- 7. Limits over the operating temperature range are guaranteed by design.
- 8. Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (I/O_VLn or I/O_VCCn) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW). Skew is defined by applying a single input to the two input channels and measuring the difference in propagation delays between the output channels.

TIMING CHARACTERISTICS - OPEN DRAIN DRIVING CONFIGURATIONS (continued)

(I/O test circuit of Figures 5 and 6, C_{LOAD} = 15 pF, driver output impedance \leq 50 Ω , R_{LOAD} = 1 M Ω)

			-40°C to +85° (Notes 6 & 7)			
Symbol	Parameter Test Conditions	Test Conditions	Min	Тур	Max	Unit
V _L = 1.65 V,	V _{CC} = 1.65 V					•
t _{PDVL-VCC}	Propagation Delay (Driving I/O V_L , V_L to V_{CC})			20	34	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			19	34	ns
t _{PZL} , t _{PZH}	Enable Time				100	ns
t _{PLZ} , t _{PHZ}	Disable Time				300	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		3			Mbps
V _L = 1.65 V,	V _{CC} = 5.5 V		1	1	Į.	·I
t _{RVCC}	I/O V _{CC} Rise Time			22	34	ns
t _{FVCC}	I/O V _{CC} Fall Time			20	27	ns
t _{RVL}	I/O V _L Rise Time			43	55	ns
t _{FVL}	I/O V _L Fall Time			6	12	ns
t _{PDVL} -VCC	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			13	26	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			19	24	ns
t _{PZL} , t _{PZH}	Enable Time				80	ns
t _{PLZ} , t _{PHZ}	Disable Time				250	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		3			Mbps
V _L = 1.8 V, V	/ _{CC} = 3.3 V		- 1		•	
t _{RVCC}	I/O V _{CC} Rise Time			34	40	ns
t _{FVCC}	I/O V _{CC} Fall Time			1	15	ns
t _{RVL}	I/O V _L Rise Time			40	48	ns
t_{FVL}	I/O V _L Fall Time			1	2	ns
t _{PDVL} -VCC	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			9	15	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			6	11	ns
t _{PZL} , t _{PZH}	Enable Time				70	ns
t _{PLZ} , t _{PHZ}	Disable Time				300	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		7			Mbps
V _L = 5.5 V, V	V _{CC} = 1.65 V		•	•	•	-
t _{RVCC}	I/O V _{CC} Rise Time			44	52	ns
t _{FVCC}	I/O V _{CC} Fall Time			1	2	ns
t _{RVL}	I/O V _L Rise Time			7	30	ns
t_{FVL}	I/O V _L Fall Time			17	23	ns
t _{PDVL} -VCC	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			10	17	ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

- 6. Typical values are for the specified V_L and V_{CC} at $T_A = +25^{\circ}C$. All units are production tested at $T_A = +25^{\circ}C$. 7. Limits over the operating temperature range are guaranteed by design.
- 8. Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (I/O_VLn or I/O_VCCn) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW). Skew is defined by applying a single input to the two input channels and measuring the difference in propagation delays between the output channels.

TIMING CHARACTERISTICS - OPEN DRAIN DRIVING CONFIGURATIONS (continued)

(I/O test circuit of Figures 5 and 6, C_{LOAD} = 15 pF, driver output impedance \leq 50 Ω , R_{LOAD} = 1 M Ω)

			-40°C to +85°C (Notes 6 & 7)		_	
Symbol	Parameter	Test Conditions	Min	Тур	Max	Unit
V _L = 5.5 V, V	/ _{CC} = 1.65 V					
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			12	24	ns
t _{PZL} , t _{PZH}	Enable Time				100	ns
t _{PLZ} , t _{PHZ}	Disable Time				300	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		3			Mbps
V _L = 5.5 V, V	_{CC} = 5.5 V					
t _{RVCC}	I/O V _{CC} Rise Time			42	50	ns
t _{FVCC}	I/O V _{CC} Fall Time			2	3	ns
t _{RVL}	I/O V _L Rise Time			44	48	ns
t _{FVL}	I/O V _L Fall Time			2	3	ns
t _{PDVL-VCC}	Propagation Delay (Driving I/O V _L , V _L to V _{CC})			4	6	ns
t _{PDVCC-VL}	Propagation Delay (Driving I/O V _{CC} , V _{CC} to V _L)			6	9	ns
t _{PZL} , t _{PZH}	Enable Time				60	ns
t _{PLZ} , t _{PHZ}	Disable Time				225	ns
t _{PPSKEW}	Part-to-Part Skew				2	ns
MDR	Maximum Data Rate		7			Mbps

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

^{6.} Typical values are for the specified V_L and V_{CC} at $T_A = +25^{\circ}C$. All units are production tested at $T_A = +25^{\circ}C$.

^{7.} Limits over the operating temperature range are guaranteed by design.

^{8.} Skew is the variation of propagation delay between output signals and applies only to output signals on the same port (I/O_VLn or I/O_VCCn) and switching with the same polarity (LOW-to-HIGH or HIGH-to-LOW). Skew is defined by applying a single input to the two input channels and measuring the difference in propagation delays between the output channels.

TEST SETUP

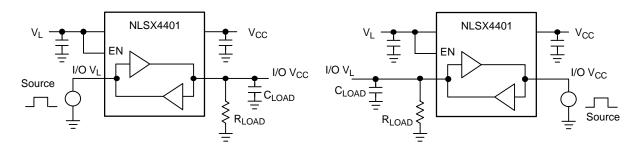


Figure 3. Rail-to-Rail Driving I/O V_L

Figure 4. Rail-to-Rail Driving I/O V_{CC}

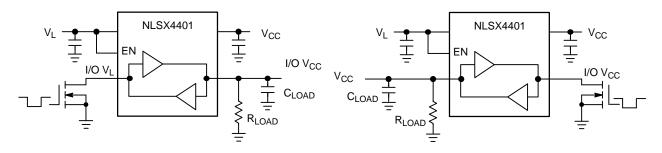


Figure 5. Open-Drain Driving I/O V_L

Figure 6. Open-Drain Driving I/O V_{CC}

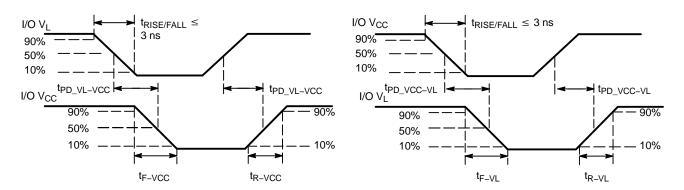
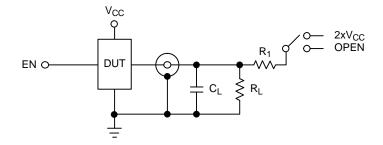


Figure 7. Definition of Timing Specification Parameters



Test	Switch	
t _{PZH} , t _{PHZ}	Open	
t _{PZL} , t _{PLZ}	2 x V _{CC}	

 C_L = 15 pF or equivalent (Includes jig and probe capacitance) R_L = R_1 = 50 $k\Omega$ or equivalent

Figure 8. Test Circuit for Enable/Disable Time Measurement

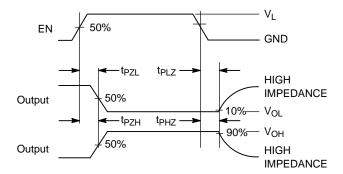


Figure 9. Timing Definitions for Propagation Delays and Enable/Disable Measurement

APPLICATIONS INFORMATION

Level Translator Architecture

The NLSX4401 auto sense translator provides bi–directional voltage level shifting to transfer data in multiple supply voltage systems. This device has two supply voltages, V_L and V_{CC} , which set the logic levels on the input and output sides of the translator. When used to transfer data from the I/O V_L to the I/O V_{CC} ports, input signals referenced to the V_L supply are translated to output signals with a logic level matched to V_{CC} . In a similar manner, the I/O V_{CC} to I/O V_L translation shifts input signals with a logic level compatible to V_{CC} to an output signal matched to V_L .

The NLSX4401 consists of a bi-directional channels that independently determines the direction of the data flow without requiring a directional pin. The one-shot circuits are used to detect the rising input signals. In addition, the one shots decrease the rise time of the output signal for low-to-high transitions.

Each input/output channel has an internal $10~k\Omega$ pull-up. The magnitude of the pull-up resistors can be reduced by connecting external resistors in parallel to the internal $10~k\Omega$ resistors.

Input Driver Requirements

The rise (t_R) and fall (t_F) timing parameters of the open drain outputs depend on the magnitude of the pull-up resistors. In addition, the propagation times (t_{PHL} / t_{PLH}), skew (t_{PSKEW}) and maximum data rate depend on the

impedance of the device that is connected to the translator. The timing parameters listed in the data sheet assume that the output impedance of the drivers connected to the translator is less than 50 k Ω .

Enable Input (EN)

The NLSX4401 has an Enable pin (EN) that provides tri–state operation at the I/O pins. Driving the Enable pin to a low logic level minimizes the power consumption of the device and drives the I/O $V_{\rm CC}$ and I/O $V_{\rm L}$ pins to a high impedance state. Normal translation operation occurs when the EN pin is equal to a logic high signal. The EN pin is referenced to the $V_{\rm L}$ supply and has Overvoltage Tolerant (OVT) protection.

Power Supply Guidelines

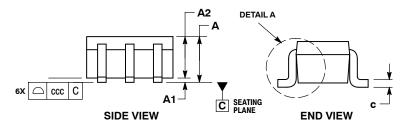
During normal operation, supply voltage V_L can be greater than, less than or equal to V_{CC} . The sequencing of the power supplies will not damage the device during the power up operation.

For optimal performance, 0.01 μF to 0.1 μF decoupling capacitors should be used on the V_{CCA} and V_{CCB} power supply pins. Ceramic capacitors are a good design choice to filter and bypass any noise signals on the voltage lines to the ground plane of the PCB. The noise immunity will be maximized by placing the capacitors as close as possible to the supply and ground pins, along with minimizing the PCB connection traces.

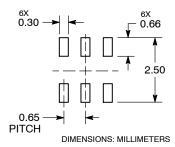
SC-88/SC70-6/SOT-363 CASE 419B-02 **ISSUE Y**

DATE 11 DEC 2012





RECOMMENDED



SOLDERING FOOTPRINT*

*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NOTES:

- DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
 CONTROLLING DIMENSION: MILLIMETERS
- CONTROLLING DIMENSION: MILLIMETERS.
 DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH,
- DIMENSIONS D AND E1 DO NOT INCLUDE MOLD FLASH, PROTRUSIONS, OR GATE BURRS. MOLD FLASH, PROTRUSIONS, OR GATE BURRS SHALL NOT EXCEED 0.20 PER END. DIMENSIONS D AND E1 AT THE OUTERMOST EXTREMES OF THE PLASTIC BODY AND DATUM H. DATUMS A AND B ARE DETERMINED AT DATUM H. DIMENSIONS b AND c APPLY TO THE FLAT SECTION OF THE LEAD BETWEEN 0.08 AND 0.15 FROM THE TIP.

- DIMENSION 6 DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 TOTAL IN EXCESS OF DIMENSION 5 AT MAXIMUM MATERIAL CONDITION. THE DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OF THE FOOT.

	MILLIMETERS			INCHES		
DIM	MIN	NOM	MAX	MIN	NOM	MAX
Α			1.10			0.043
A1	0.00		0.10	0.000		0.004
A2	0.70	0.90	1.00	0.027	0.035	0.039
b	0.15	0.20	0.25	0.006	0.008	0.010
С	0.08	0.15	0.22	0.003	0.006	0.009
D	1.80	2.00	2.20	0.070	0.078	0.086
E	2.00	2.10	2.20	0.078	0.082	0.086
E1	1.15	1.25	1.35	0.045	0.049	0.053
е	0.65 BSC		0.026 BSC			
L	0.26	0.36	0.46	0.010	0.014	0.018
L2	0.15 BSC			0.006 BSC		
aaa	0.15			0.006		
bbb	0.30			0.012		
ccc	0.10			0.004		
ddd	0.10			0.004		

GENERIC MARKING DIAGRAM*



XXX = Specific Device Code

= Date Code* = Pb-Free Package

(Note: Microdot may be in either location)

- *Date Code orientation and/or position may vary depending upon manufacturing location.
- *This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot " ■", may or may not be present.

STYLES ON PAGE 2

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DATE 11 DEC 2012

STYLE 1: PIN 1. EMITTER 2 2. BASE 2 3. COLLECTOR 1 4. EMITTER 1 5. BASE 1 6. COLLECTOR 2	STYLE 2: CANCELLED	STYLE 3: CANCELLED	STYLE 4: PIN 1. CATHODE 2. CATHODE 3. COLLECTOR 4. EMITTER 5. BASE 6. ANODE	STYLE 5: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 6: PIN 1. ANODE 2 2. N/C 3. CATHODE 1 4. ANODE 1 5. N/C 6. CATHODE 2
STYLE 7: PIN 1. SOURCE 2 2. DRAIN 2 3. GATE 1 4. SOURCE 1 5. DRAIN 1 6. GATE 2	STYLE 8: CANCELLED	STYLE 9: PIN 1. EMITTER 2 2. EMITTER 1 3. COLLECTOR 1 4. BASE 1 5. BASE 2 6. COLLECTOR 2	STYLE 10: PIN 1. SOURCE 2 2. SOURCE 1 3. GATE 1 4. DRAIN 1 5. DRAIN 2 6. GATE 2	STYLE 11: PIN 1. CATHODE 2 2. CATHODE 2 3. ANODE 1 4. CATHODE 1 5. CATHODE 1 6. ANODE 2	STYLE 12: PIN 1. ANODE 2 2. ANODE 2 3. CATHODE 1 4. ANODE 1 5. ANODE 1 6. CATHODE 2
STYLE 13: PIN 1. ANODE 2. N/C 3. COLLECTOR 4. EMITTER 5. BASE 6. CATHODE	STYLE 14: PIN 1. VREF 2. GND 3. GND 4. IOUT 5. VEN 6. VCC	STYLE 15: PIN 1. ANODE 1 2. ANODE 2 3. ANODE 3 4. CATHODE 3 5. CATHODE 2 6. CATHODE 1	STYLE 16: PIN 1. BASE 1 2. EMITTER 2 3. COLLECTOR 2 4. BASE 2 5. EMITTER 1 6. COLLECTOR 1	STYLE 17: PIN 1. BASE 1 2. EMITTER 1 3. COLLECTOR 2 4. BASE 2 5. EMITTER 2 6. COLLECTOR 1	STYLE 18: PIN 1. VIN1 2. VCC 3. VOUT2 4. VIN2 5. GND 6. VOUT1
STYLE 19: PIN 1. I OUT 2. GND 3. GND 4. V CC 5. V EN 6. V REF	STYLE 20: PIN 1. COLLECTOR 2. COLLECTOR 3. BASE 4. EMITTER 5. COLLECTOR 6. COLLECTOR	STYLE 21: PIN 1. ANODE 1 2. N/C 3. ANODE 2 4. CATHODE 2 5. N/C 6. CATHODE 1	STYLE 22: PIN 1. D1 (i) 2. GND 3. D2 (i) 4. D2 (c) 5. VBUS 6. D1 (c)	STYLE 23: PIN 1. Vn 2. CH1 3. Vp 4. N/C 5. CH2 6. N/C	STYLE 24: PIN 1. CATHODE 2. ANODE 3. CATHODE 4. CATHODE 5. CATHODE 6. CATHODE
STYLE 25: PIN 1. BASE 1 2. CATHODE 3. COLLECTOR 2 4. BASE 2 5. EMITTER 6. COLLECTOR 1	STYLE 26: PIN 1. SOURCE 1 2. GATE 1 3. DRAIN 2 4. SOURCE 2 5. GATE 2 6. DRAIN 1	STYLE 27: PIN 1. BASE 2 2. BASE 1 3. COLLECTOR 1 4. EMITTER 1 5. EMITTER 2 6. COLLECTOR 2	STYLE 28: PIN 1. DRAIN 2. DRAIN 3. GATE 4. SOURCE 5. DRAIN 6. DRAIN	STYLE 29: PIN 1. ANODE 2. ANODE 3. COLLECTOR 4. EMITTER 5. BASE/ANODE 6. CATHODE	STYLE 30: PIN 1. SOURCE 1 2. DRAIN 2 3. DRAIN 2 4. SOURCE 2 5. GATE 1 6. DRAIN 1

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